Faster Time to Market for IC Designs

Air Cavity Plastic QFN Packages
Overmolded Plastic QFN/DFN Packages
Ceramic, Laminate, COF, COB
Assembly Services from Prototype Design Validation to Full Production
Wafer Processing from Quick-Turn Runs to Volume Production
Packages

*We’ll help you create a package solution that gets your design to market faster. Choose from hundreds of IC packaging options for complex semiconductor, RF/wireless, solar, MEMS, medical and biotech applications.*

**Open-molded/Pre-molded Air Cavity Plastic QFN/SOIC Packages (OmPP)**
- Body sizes from 3x3 mm to 12x12 mm
- Lead pitch sizes from 0.80 mm to 0.40 mm
- Gold plated for superior bondability
- JEDEC standard outlines
- Matching ceramic, plastic, quartz, and glass lids with epoxy seals
- Available in high volumes and off-the-shelf stock for rapid delivery
- RoHS and REACH compliant green molding compound

**Open Cavity Plastic Packages (OCPP)—The ideal platform for new IC prototypes**

We can convert any existing plastic package, whether dummy, electrical test reject, or excess inventory, into an open cavity package ready to be assembled with your new device.
- IC prototypes in any plastic package
- Mechanically and electronically identical to production parts
- Turn-around in 24 hours or less
- Ideal for rapid prototype assembly, design verification, and customer samples
- No minimum orders

**Custom Air Cavity Packages**
- Custom body size/shape
- Custom lead count
- Custom materials
- Made-to-order lids

**Plastic Overmolded Packages—Packaging and assembly for higher volume applications**
- Overmolded metal leadframe arrays
- Saw-singulated chip scale packages including QFN and DFN
- Wire bonded devices
- Flip chip devices
Quick-Turn Assembly Services

Easily ramp up from prototype design validation to full production onsite in San Diego, California

High-Volume Precision Die Attach

Fully automated die attach and die placement services for prototype and volume assembly
- Accuracy within ± 10 μm
- Die bond or flip chip attach

Wire Bond Capabilities

Our advanced equipment enables us to control wire bond lengths with a high degree of precision, which means consistent electrical performance for your device.
- Gold wire bonding with 0.6 to 3.0 mils diameters
- Gold, aluminum, or copper wire capability
- Heavy aluminum wire bond 5 to 20 mils

Encapsulation

Choose the level of protection and/or accessibility that you need.
- Flattened/remolded
- Open cavity with frame or lid
- Custom molded
- Clear encapsulant
- Partial open cavity
- Glob top
- Overmold

Flip Chip Assembly

Flexible process and advanced equipment to meet your unique requirements
- Thermosonic, thermo-compression, and solder reflow bonding
- Low temperature solders
- Devices can be attached to within ± 5 μm placement accuracy
- Assembly for μBGA, standard flip chip, and VCSEL/photodiode/sensor bonding

Custom Assembly

For low-volume/complex-mix packages
- Stacked die
- Chip on Board (COB)
- Chip on Flex (COF)
- System in Package (SiP)
- Multi-chip Module (MCM)
- Micro-Electro Mechanical Systems (MEMS)
- Packages with embedded thermal sensors
- Laminate array
- Ball Grid Array (BGA)
Wafer Preparation Services—Minimize yield loss with precision wafer processing

Quik-Pak's newly expanded ISO Class 7 wafer preparation facility can accommodate everything from small production runs to volume wafer handling. The company’s fully automated equipment provides high throughput and maximum yield to get your device to market faster.

Wafer Dicing
High-precision, quick-turn dicing services for a variety of substrates are available. Our experienced operators and advanced equipment enable us to provide superior service on a variety of projects.

- Silicon, Silicon Carbide (SiC), Gallium Nitride (GaN)
- Ceramic, laminates, glass, quartz, and sapphire
- Wafers up to 12" (300 mm)
- Multi-project wafers (MPW), reticles, partial wafers and bumped wafers

Pick and Place
Select specific die and place into the media of your choice

- High mix die sorting for multi-project wafers
- Die sorting into Gel-Pak®, waffle pack, or on tape

Wafer Backgrinding
Reduces surface roughness, improves die strength, and reduces wafer warpage for higher yields

- Backgrinding down to 50 μm
- Singulated die thinning
- Bumped wafer backgrinding
- Laser marking
- Low surface roughness